ComX Computers
Product Specification Sheet

MB-GX570SAM+W

Gigabyte X570S Aorus Master AMD X570 AMD Ryzen AM4 Socket Motherboard

Product Overview

Gigabyte X570S Aorus Master + Wifi: AMD AM4 mb - with 14+2 phase digital VRM, pre-mounted I/O shield with thermal armor + RGB Fusion 2.0 with on-board RGB display (multi zones), Addressable LED Strip Support, on-board buttons (power + reset + clear



Specifications

Overview:

GIGABYTE X570S motherboards feature upgraded power solution, passive and silent thermal design, and PCIe 4.0 components to keep your gaming system up to fast and powerful, even under heavy workloads.

Features:

UNPARALLELED PERFORMANCE
To unleash the full potential of the latest AMD Ryzen™ 5000 series processors, the motherboard requires the best CPU power, memory and IO design. With the best quality components and GIGABYTE R&D design capability, X570S AORUS MASTER is a true beast among motherboards.

Direct Power Design
GIGABYTE X570S Motherboards are equipped with best in class power solution to release the full potential of the latest AMD Ryzen™ 5000 Series CPUs. The VRM power design includes MOSFETs which Vcore and SOC accompanied by digital PWM, premium chokes and high quality capacitors to offer extraordinary stability and precision to the high performance CPU. In addition, Six-layered PCB and comprehensive thermal solution allows enthusiasts to enjoy the extreme overclocking performance without compromise.

GIGABYTE Active OC Tuner
With GIGABYTE's exclusive Active OC Tuner BIOS function, CPU* can work with AMD P.B.O. for gaming and other light workload applications with the highest CPU boost clock, but when the applications require all CPU cores horsepower, it automatically switches to the Manual OC mode where it can utilize the high frequency for all the CPU cores.

- Active OC Tuner switches profile based on user scenario automatically

Memory Layout - Daisy Chain Design
With the optimized daisy-chain routing, GIGABYTE X570S motherboards provide a proven speed of up to DDR4-5400+ MHz

with high density memory modules*. Optimized daisy-chained routing eliminates the stub effect, pushes the one DIMM per channel in dual channel interleaving mode to hit higher memory frequencies, and provides professional gamers a denser and faster system memory experience.

Support for DDR4 XMP Up to 5400MHz and Beyond*
AORUS is offering a tested and proven platform that ensures proper compatibility with profiles up to 5400MHz and beyond. All users need to do to attain this performance boost is to ensure that their memory module is XMP capable and that the XMP function is activated and enabled on their AORUS motherboard.

Single 32GB Support
With populated 4 DIMMs per channel on GIGABYTE X570 motherboards, the maximum memory capacity support is 128GB. For users who always run out of memory capacity, they are able to enjoy more bandwidth now for memory-intensive application such as rendering and video editing.

3X PCIe 4.0 Slot
Reinforces PCIe 4.0 x16 or 2 x8, x4 bandwidth with lower impedance.

4X M.2 PCIe 4.0 Slot
M.2 PCIe 4.0 x4 slot with lower impedance.

PCIe 4.0 Turbo B-Clock
External clock generator for PCIe 4.0 overclocking.

PCIe 4.0 Active Switch
Switch PCIe 4.0 x16 into PCIe 4.0 x8/x8 with strengthened signal.

ADVANCED THERMAL SOLUTION
X570S AORUS MASTER uses an unprecedented and innovative thermal design to ensure the best CPU, Chipset, SSD stability and low temperatures under full loading application and gaming.

Direct-Touch Heatpipe II
With an extra large 8mm heatpipe and made by a new manufacturing process which has narrowed down the gap between the heatpipe and heatsink. The new Direct-Touch Heatpipe II greatly helps to dissipate the heat on MOSFETs.

2X Copper PCB
2X Copper PCBs design effectively lower the component temperature by its high thermal conductivity and low impedance.

Fins-Array II
Fins-Array II uses brand new louvered stacked-fins design which not only increases surface area by 300% compared to traditional heatsinks, but also improves thermal efficiency with better airflow and heat dissipation.

9 W/mK Thermal Conductivity Pad
By using 1.5mm thicker 9 W/mK thermal conductivity pads, it can transfer 4x more of heat dissipation compared to traditional thermal pads in same time.

M.2 Thermal Guard III
M.2 Thermal Guard III constructed with 2.6X optimized heat dissipation surface and double-sided M.2 heatsinks to prevent throttling and bottlenecks on high-speed/ large capacity of PCIe 4.0 M.2 SSDs.

Fins-Array II
Fins-Array II uses brand new louvered stacked fins technology which is usually only used on industrial equipment that need compact heat exchangers. It has a special secondary fins structure that enhances heat transfer performance.

Louver Directed Flow
Heat flow that goes through fins will enter from the leading edge of the louver and is then directed by other louvers or fins. This louver directed flow can greatly improve heat transfer performance.

Circulation Zone
Because of pressure difference and flow separation, a circulation zone will be formed between louvered fins. This circulation will cause flow entrain and eject in the vortice form which improves thermal efficiency.

NanoCarbon Coated Fins Array Heatsink
As CPUs get more powerful, VRM modules get hotter under ultra high performance. Being the first adopters among industry using NanoCarbon as coating material to enhance thermal radiation speed up heat dissipation. Nanocarbon is coated onto the heatsink through electrostatic adhesion. The coating material covers the entire finned heatsink with 200um in thickness. In that way, heat is dissipated more quickly. The tests show 10% cooler with the NanoCarbon coating.

Direct-Touch Heatpipe II
With an extra large 8mm heatpipe and made by a new manufacturing process which has narrow down the gap between the heatpipe and heatsink. The new Direct-Touch Heatpipe II greatly helps to dissipate the heat on MOSFETs.

M.2 Thermal Guard III
Continuing the advantages of M.2 Thermal Guard II design which using the double-sided thermal pads to elevate the height of M.2 heatsink as increasing surface area to dissipate heats on M.2 SSDs. M.2 Thermal Guard III constructed with 2.6X optimized heat dissipation surface to prevent throttling and bottleneck that high-speed/ large capacity of PCIe 4.0 M.2 SSDs may cause, especially under heavy workload.

M.2 Thermal Guard III
GIGABYTE motherboards promise the consistent cooling and high performance for the users to avoid throttling from the overheating.

Smart Fan 6
Smart Fan 6 contains several unique cooling features that ensure gaming PC maintain its performance while staying cool and quiet. Multiple fan headers can support PWM/DC fan and pump, and users can easily define each fan curve based on different temperature sensors across the board via intuitive user interface.

High Current Support
Each fan headers support PWM and DC fan and Water cooling Pump , and up to 24W (12V x 2A) with Over-Current Protection

Precision Control
7 temperature/fan speed control points for precise fan curve

Dual Curve Mode
Slope/Stair dual mode for different user scenario

Fan Stop
Fan can stop completely below users' specified temperature point

Improve fan curve UI
We increase control points from 5 to 7 and larger fan speed graph for precise and easier fan curve control.

Slope/Stair dual graph mode
Fan curve can be quickly switch with Slope and Stair modes for different user scenario. Slope is traditional and intuitive linear fan speed curve. With newly added Stair non-linear mode, fan keeps at same speed between specified temperature interval.

Manual Input
For advanced users, we provide fan speed manual input for more precise control.

EZ Tuning
Use can place 4 EZ Tuning points at rough temperature/fan speed, and Smart Fan 6 can quickly generate a fan curve.

Fan curve profile
Fan curve profile can be saved in BIOS ROM, profile will be kept after updating BIOS.

Fan Stop
Achieve fan silence. With Fan Stop, map any fan to stop completely when temperatures drop below a specified threshold. Which fan stops, based on readings from which sensor, and at what temperature-all of it can be customized to your liking.

Noise Detection
With the new Noise Detection function, you can monitor noise level of all devices including fans, CPU coolers, graphics card, etc. in real time, and you can determine how fast your fan speed needs to be. Our bundled Noise Detection cable doesn't include any sound recording function, it simply detects sound pressure while protecting your privacy.

NEXT GENERATION CONNECTIVITY
A Flagship product needs to be future-proof so your system stays up-to-date with the latest technology. X570S AORUS MASTER provides all next generation network, storage, and WIFI connectivity to keep you up to speed.

First adopter on 2.5GbE LAN onboard
Adoption of 2.5G LAN provide up to 2.5 GbE network connectivity, with at least 2X faster transfer speeds compared to general 1GbE networking, perfectly designed for gamers with ultimate online gaming experience.

- Support Multi-Gig(10/100/1000/2500Mbps) RJ-45 Ethernet

Intel® 802.11ax WIFI 6E
Intel® latest Wireless solution 802.11ax WIFI 6E with new dedicated 6GHz band, enables gigabit wireless performance, provides smooth video streaming, better gaming experience, few dropped connections and speeds up to 2.4Gbps*. Moreover, Bluetooth 5 provides 4X range over BT 4.2 and with faster transmission.

Benefit of WIFI 6E

- Dedicated spectrum in 6GHz band for less interference
- 5.5X throughput than 802.11ac 1x1*
- 4X better network capacity, no traffic jams especially in those dense area with lots of devices
- Network efficiency increase for better user experience

WIFI 6E Advantage
Spectrum congestion is huge problem in current WIFI environment nowadays because too many devices all use existing 2.4GHz and 5GHz spectrum, and it cause unreliable connection and slower speed. WIFI 6E is extended standard to WIFI 6, and it use dedicated 6GHz band that it provides not only brand new frequency to transfer data, but also spacious spectrum for future more devices. With WIFI 6E, users can enjoy faster connection and stronger signal than before.

AORUS Antenna Supports Tri-Band with Better WIFI Signal

- All new antenna supported Tri-Band 802.11ax WIFI 2.4GHz, 5GHz and 6GHz better signal strength compared to traditional antenna design
- AORUS Antenna with smart antenna function for the best WIFI signal transmitting
- Multiple angle tilt and magnetic base for the best signal strength direction and location

Connecting the Future - USB 3.2 Gen 2x2 Type-C®
Featuring the USB 3.2 Gen 2x2 design which is doubled the performance than previous generation of USB 3.2 Gen 2. It works

up to 20Gbps ultra-fast data transfer while connecting to USB 3.2 compliant peripherals. Through the USB Type-C® connector, users can enjoy the flexibility of reversible connection to access and store massive amounts of data rapidly.

ESS SABRE reference DAC ES9118

- ESS SABRE reference DAC (ESS 9118)
- Hyperstream Dynamic Range (SNR 125dB)
- High-Res music (32bit, 192KHz PCM)
- Super low THD+N (THD+N -112db)

True High-Fidelity Music (Realtek ALC1220-VB)
ALC1220 120dB(A) SNR HD Audio with Smart Headphone Amp can automatically detect impedance of your head-worn audio device, to prevent issues such as low volume and distortion. With the new VB series audio controller, it can stream your voice to the world vibrantly with both front/rear microphone SNR up to 110/114dB(A).

Audiophile Grade Capacitors (WIMA , Nichicon Fine Gold)
To ensure a studio-quality experience, WIMA and Nichicon Fine Gold capacitors are used to provide power to the overall system.

Precision Audio Stream (TXC OSCILLATOR)
Provides precise time triggers to Digital-Analog Converters. High resistance to corrosion and oxidation.

Hi-Res Audio
Hi-Res Audio certified, meaning that the product is capable of reproducing frequencies up to 40kHz or above which ensures user with the best audio quality at all times.

DTS :X® Ultra
Recreates an authentic, spatially accurate 3D audio experience for gaming over any headphones or speakers. Supports channel-based, scene based and object-based audio. Provides out-of-the-box calibration for a range of headphones and speakers. Provides post-processing enhancements and device level tuning for DTS® codecs. DTS Sound Unbound* leverage Microsoft Spatial, enabling the the most believable, 3D audio experience for games. Immersion through DTS Headphone:X means in the sonic landscape, stationary and moving sounds can be heard from above, below or around the listener. Sounds pass around the listener with amazing externalization and accurate localization.

DEFINITIVE AESTHETICS
X570S AORUS MASTER features RGB FUSION 2.0 to offer lighting effected options and customized settings with outstanding aesthetics, and able to let enthusiasts building a stylish and unique gaming PC.

Multi-Zone Light Show Design
Now offering more LED customizations than ever, users can truly adapt their PC to represent their lifestyle. With full RGB support and a redesigned RGB Fusion 2.0 application, the user has complete control over the LEDs which surround the motherboard.

RGB Fusion 2.0
With an integrated intuitive user interface, the RGB Fusion 2.0 provides you a better solution for customizing the lighting effects across all supported devices. From motherboards, graphics cards to the peripheral products, you can personalize your gaming rig with your own style and show off your build by sharing the profiles. In addition, the new gaming mode makes the lighting effects interactive with selected games to bring you the most immersive gaming experience.

New User Interface
All new EASY MODE shows important hardware information in one page including CPU clock, Memory, Storage, Fan.

My Favorites

Add constantly used items into the favorite menu for quick access.

Storage Information
Show all kinds of storage information including SATA, PCIE and M.2 interface.

Changelog
List all changes before saving and exiting bios. Quickly review overall settings modification.

Intuitive Load Line Curve
Clearly show each loadline calibration setting in an intuitive curve graph.

MultiKey
A multi-function reset button that can be reconfigured to other function in BIOS for different user scenarios.

RGB Switch
Turn off all lighting effect on motherboard.

Direct-To-BIOS
Boot into BIOS menu directly without pressing any keyboard button.

Safe Mode
Boot into BIOS safe mode to change specific option without losing other BIOS settings.

EasyTune™
GIGABYTE's EasyTune™ is a simple and easy-to-use interface that allows users to fine-tune their system settings or adjust system and memory clocks and voltages in a Windows environment. With Smart Quick Boost, one click is all it takes to automatically overclock your system, giving an added performance boost when you need it the most.

ULTRA DURABLE
GIGABYTE is reputable for its product durability and high quality manufacturing process. Needless to say, we use the best components we can find for the GIGABYTE Motherboard and reinforce every slot to make each of them solid and durable.

Q-Flash Plus
With GIGABYTE Q-Flash Plus, you don't need to install the CPU, memory and graphics card nor enter the BIOS menu to flash the BIOS. Just download and save a new BIOS file (rename to gigabyte.bin) on the USB flash drive, then press the dedicated Q-Flash Plus button and you're good to go!

Industry Leading Ultra Durable™ PCIe Armor
The innovative one piece stainless steel shielding design from GIGABYTE reinforces the PCIe connectors to provide the extra strength required to support heavy graphics cards.

Ultra Durable™ Memory Armor
AORUS' exclusive one piece stainless steel shielding design prevents against PCB distortion/twisting and plate bending, in addition to preventing any possible ESD interference.

Solid Pin Power Connectors
AORUS motherboards feature solid plated ATX 24pin & ATX 12V 8pin + 4pin power connectors to offer a stable power supply during CPU overloading.

Solid Pin Power connector advantages

- Larger contact area for electricity

- More metal quantity to sustain higher power and generated heat
- Ultra durable and longer lifespan

Specifications:

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Specifications	
Product Code	MB-GX570SAM+W
CPU	1. AMD Socket AM4, support for: AMD Ryzen 5000 Series Processors/ AMD Ryzen 4000 G-Series Processors/ AMD Ryzen 3000 Series Processors/ AMD Ryzen 3000 G-Series Processors/ AMD Ryzen 2000 Series Processors/ AMD Ryzen 2000 G-Series Processors
Chipset	1. AMD X570
Memory	1. AMD Ryzen 5000 Series Processors/AMD Ryzen 4000 G-Series Processors/ AMD Ryzen 3000 Series Processors:
	Support for DDR4 3200/2933/2667/2400/2133 MHz memory modules
	2. AMD Ryzen 3000 G-Series Processors/AMD Ryzen 2000 Series Processors/ AMD Ryzen 2000 G-Series Processors:
	Support for DDR4 2933/2667/2400/2133 MHz memory modules
	3. 4 x DDR4 DIMM sockets supporting up to 128 GB (32 GB single DIMM capacity) of system memory
	4. Dual channel memory architecture
	5. Support for ECC Un-buffered DIMM 1Rx8/2Rx8 memory modules
	6. Support for non-ECC Un-buffered DIMM 1Rx8/2Rx8/1Rx16 memory modules
	7. Support for Extreme Memory Profile (XMP) memory modules
Audio	1. Realtek ALC1220-VB audio CODEC
	* The front panel line out jack supports DSD audio.
	2. ESS SABRE9118 DAC chip
	3. Support for DTS:X Ultra
	4. High Definition Audio
	5. 2/4/5.1/7.1-channel
	6. Support for S/PDIF Out
LAN	1. Intel 2.5GbE LAN chip (2.5 Gbps/1 Gbps/100 Mbps)
Wireless Communication module	Intel Wi-Fi 6E AX210
	1. WIFI a, b, g, n, ac, ax, supporting 2.4/5/6 GHz carrier frequency bands
	2. BLUETOOTH 5.2
	3. Support for 11ax 160MHz wireless standard and up to 2.4 Gbps data rate
	* Actual data rate may vary depending on environment and equipment.

Expansion Slots	1 x PCI Express x16 slot (PCIEX16), integrated in the CPU:
	1. AMDRyzen 5000 Series Processors/AMDRyzen 3000 Series Processors support PCIe 4.0 x16 mode
	2. AMDRyzen 4000G-SeriesProcessors/AMDRyzen 2000 Series Processors support PCIe 3.0 x16 mode
	3. AMDRyzen 3000G-SeriesProcessors/AMDRyzen 2000 G-Series Processors support PCIe 3.0 x8 mode
	1 x PCI Express x16 slot (PCIEX8), integrated in the CPU:
	1. AMDRyzen 5000 Series Processors/AMDRyzen 3000 Series Processors support PCIe 4.0 x8 mode
	2. AMDRyzen 4000G-SeriesProcessors/AMDRyzen 2000 Series Processors support PCIe 3.0 x8 mode
	3. AMDRyzen 3000G-SeriesProcessors/AMDRyzen 2000 G-Series Processors do not support this slot
	* For optimum performance, if only one PCI Express graphics card is to be installed, be sure to install it in the PCIEX16 slot.
	* The PCIEX8 slot shares bandwidth with the PCIEX16 slot. When the PCIEX8 slot is populated, the PCIEX16 slot operates at up to x8 mode.
	1 x PCI Express x16 slot (PCIEX4), integrated in the Chipset:
	1. Supporting PCIe 4.0* /3.0 x4 mode
	* For AMD Ryzen 5000 Series Processors/AMD Ryzen 3000 Series Processors only.
	* The PCIEX4 slot shares bandwidth with the M2C_SB connector. The PCIEX4 slot becomes unavailable when a device is installed in the M2C_SB connector.
Multi-Graphics Technology	1. Support for AMD Quad-GPU CrossFire and 2-Way AMD CrossFire technologies
	For AMD Ryzen 5000 Series Processors/AMD Ryzen 4000 G-Series Processors/AMD Ryzen 3000 Series Processors/AMD Ryzen 2000 Series Processors only.

Storage Interface	1 x M.2 connector (M2A_CPU), integrated in the CPU, supporting Socket 3, M key, type 2242/2280/22110 SSDs:
	1. AMD Ryzen 5000 Series Processors/AMD Ryzen 3000 Series Processors support SATA and PCIe 4.0 x4/x2 SSDs
	2. AMD Ryzen 4000 G-Series Processors/AMD Ryzen 3000 G-Series Processors/AMDRyzen 2000SeriesProcessors/AMDRyzen 2000 G-Series Processors support SATA and PCIe 3.0 x4/x2 SSDs
	1 x M.2 connector (M2B_SB), integrated in the Chipset, supporting Socket 3, M key, type 2242/2280/22110 SSDs:
	1. Supporting PCIe 4.0* /3.0 x4/x2 SSDs
	* For AMD Ryzen 5000 Series Processors/AMD Ryzen 3000 Series Processors only.
	2 x M.2 connectors (M2C_SB/M2D_SB), integrated in the Chipset, supporting Socket 3, M key, type 2242/2280/22110 SSDs:
	1. Supporting SATA and PCIe 4.0* /3.0 x4/x2 SSDs
	* For AMD Ryzen 5000 Series Processors/AMD Ryzen 3000 Series Processors only.
	6 x SATA 6Gb/s connectors, integrated in the Chipset:
	1. Support for RAID 0, RAID 1, and RAID 10
	* Refer to "1-9 Internal Connectors, " for the installation notices for the M.2 and SATA connectors.
USB	CPU:
	1. 2 x USB 3.2 Gen 2 Type-A ports (red) on the back panel
	2. 2 x USB 3.2 Gen 1 ports on the back panel
	Chipset+ASMedia USB 3.2 Gen 2x2 Controller:
	1. 1 x USB Type-C port on the back panel, with USB 3.2 Gen 2x2 support
	Chipset:
	1. 1 x USB Type-C port with USB 3.2 Gen 2 support, available through the internal USB header
	2. 3 x USB 3.2 Gen 2 Type-A ports (red) on the back panel
	3. 4 x USB 3.2 Gen 1 ports, available through the internal USB headers
	Chipset+2 USB 2.0 Hubs:
	1. 8 x USB 2.0/1.1 ports (4 ports on the back panel, 4 ports available through the internal USB headers)

Internal I/O Connectors	1. 1 x 24-pin ATX main power connector
	2. 2 x 8-pin ATX 12V power connectors
	3. 1 x CPU fan header
	4. 1 x water cooling CPU fan header
	5. 4 x system fan headers
	6. 4 x system fan/water cooling pump headers
	7. 2 x addressable LED strip headers
	8. 2 x RGB LED strip headers
	9. 1 x CPU cooler LED strip/RGB LED strip header
	10. 4 x M.2 Socket 3 connectors
	11. 6 x SATA 6Gb/s connectors
	12. 1 x front panel header
	13. 1 x front panel audio header
	14. 1 x USB Type-C header, with USB 3.2 Gen 2 support
	15. 2 x USB 3.2 Gen 1 headers
	16. 2 x USB 2.0/1.1 headers
	17. 1 x noise detection header
	18. 1 x Trusted Platform Module (TPM) header (2x6 pin, for the GC-TPM2.0_S module only)
	19. 1 x Thunderbolt add-in card connector
	20. 2 x temperature sensor headers
	21. 1 x power button
	22. 1 x reset button
	23. 1 x Clear CMOS jumper
	24. Voltage Measurement Points
Back Panel Connectors	1. 1 x Q-Flash Plus button
	2. 1 x Clear CMOS button
	3. 2 x SMA antenna connectors (2T2R)
	4. 1 x USB Type-C port, with USB 3.2 Gen 2x2 support
	5. 5 x USB 3.2 Gen 2 Type-A ports (red)
	6. 2 x USB 3.2 Gen 1 ports
	7. 4 x USB 2.0/1.1 ports
	8. 1 x RJ-45 port
	9. 1 x optical S/PDIF Out connector
	10. 5 x audio jacks
I/O Controller	1. iTE I/O Controller Chip

H/W Monitoring	1. Voltage detection
	2. Temperature detection
	3. Fan speed detection
	4. Water cooling flow rate detection
	5. Overheating warning
	6. Fan fail warning
	7. Fan speed control
	* Whether the fan (pump) speed control function is supported will depend on the fan (pump) you install.
	8. Noise detection
BIOS	1. 1 x 256 Mbit flash
	2. Use of licensed AMI UEFI BIOS
	3. PnP 1.0a, DMI 2.7, WfM 2.0, SM BIOS 2.7, ACPI 5.0
Unique Features	1. Support for APP Center
	* Available applications in APP Center may vary by motherboard model. Supported functions of each applicationmay also vary depending onmotherboard specifications.
	@BIOS
	EasyTune
	Fast Boot
	Game Boost
	ON/OFF Charge
	RGB Fusion
	Smart Backup
	System Information Viewer
	2. Support for Q-Flash Plus
	3. Support for Q-Flash
	4. Support for Xpress Install
Bundled Software	1. Norton Internet Security (OEM version)
	2. cFosSpeed
Operating System	1. Support for Windows 10 64-bit
Form Factor	1. ATX Form Factor; 30.5cm x 24.4cm

Product Information Online

For the latest product information, availability and purchasing details, please visit the product page:

Product page:
https://www.comx-computers.co.za/MB-GX570SAM-W-Gigabyte-X570S-Aorus-Master-AMD-X570-AMD-Ryzen-AM4-Socket-Motherboard-p-257563.php

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